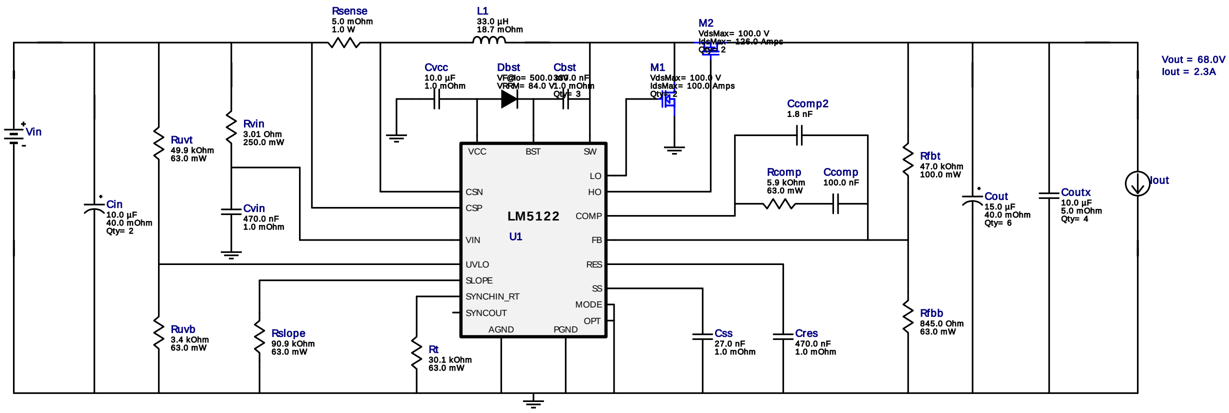
# WEBENCH® Design Report

VinMin = 22.0V
VinMax = 26.0V
Vout = 68.0V
Iout = 2.3A

Device = LM5122MH/NOPB
Topology = Boost
Created = 2021-09-10 00:24:04.684
BOM Cost = NA
BOM Count = 37
Total Pd = 6.92W

Design : 210 LM5122MH/NOPB
LM5122MH/NOPB 22V-26V to 68.00V @ 2,3A



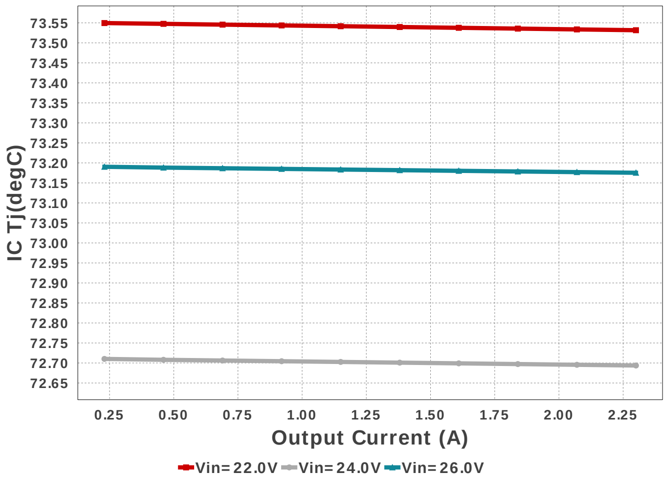

## Electrical BOM

| Name | Manufacturer | Part Number | Properties | Qty | Price | Footprint |
|---|---|---|---|---|---|---|
| Cbst | MuRata | GRM21AR72A334KAC5L<br>Series= X7R | Cap= 330.0 nF<br>ESR= 1.0 mOhm<br>VDC= 100.0 V<br>IRMS= 0.0 A | 3 | $0.11 | 0805 7 mm² |
| Ccomp | AVX | 08053C104JAZ2A<br>Series= X7R | Cap= 100.0 nF<br>VDC= 25.0 V<br>IRMS= 0.0 A | 1 | $0.06 | 0805 7 mm² |
| Ccomp2 | TDK | C2012C0G1H182K060AA<br>Series= C0G/NP0 | Cap= 1.8 nF<br>VDC= 50.0 V<br>IRMS= 0.0 A | 1 | $0.04 | 0805 7 mm² |
| Cin | Panasonic | 50SVPF10M<br>Series= SVPF | Cap= 10.0 uF<br>ESR= 40.0 mOhm<br>VDC= 50.0 V<br>IRMS= 2.5 A | 2 | $0.41 | CAPSMT_62_F61 74 mm² |
| Cout | Panasonic | 100SXV15M<br>Series= SXV | Cap= 15.0 uF<br>ESR= 40.0 mOhm<br>VDC= 100.0 V<br>IRMS= 2.35 A | 6 | $1.18 | CAPSMT_62_E12 106 mm² |
| Coutx | TDK | C5750X7S2A106M230KB<br>Series= X7S | Cap= 10.0 uF<br>ESR= 5.0 mOhm<br>VDC= 100.0 V<br>IRMS= 6.45 A | 4 | $0.86 | 2220 54 mm² |
| Cres | Taiyo Yuden | TMK212BJ474KD-T<br>Series= X5R | Cap= 470.0 nF<br>ESR= 1.0 mOhm<br>VDC= 20.0 V<br>IRMS= 0.0 A | 1 | $0.02 | 0805 7 mm² |
| Css | MuRata | GRM155R71A273KA01D<br>Series= X7R | Cap= 27.0 nF<br>ESR= 1.0 mOhm<br>VDC= 10.0 V<br>IRMS= 0.0 A | 1 | $0.01 | 0402 3 mm² |
| Cvcc | Taiyo Yuden | EMK212BJ106KG-T<br>Series= X5R | Cap= 10.0 uF<br>ESR= 1.0 mOhm<br>VDC= 16.0 V<br>IRMS= 0.0 A | 1 | $0.03 | 0805 7 mm² |

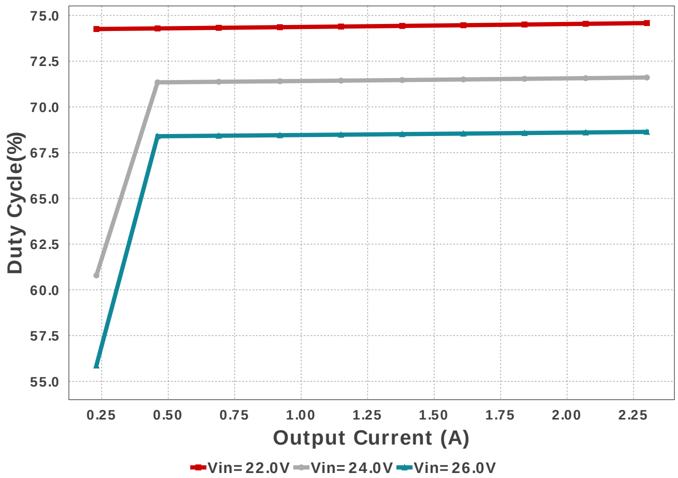
| Name | Manufacturer | Part Number | Properties | Qty | Price | Footprint |
|---|---|---|---|---|---|---|
| Cvin | MuRata | GRM21BR71H474KA88L<br>Series= X7R | Cap= 470.0 nF<br>ESR= 1.0 mOhm<br>VDC= 50.0 V<br>IRMS= 0.0 A | 1 | $0.08 | 0805 7 mm$^2$ |
| Dbst | CUSTOM | CUSTOM | VF@Io= 500.0 mV<br>VRRM= 84.0 V | 1 | NA | CUSTOM 0 mm$^2$ |
| L1 | Coilcraft | XAL1510-333MEB | L= 33.0 µH<br>18.7 mOhm | 1 | $2.27 | XAL1510 320 mm$^2$ |
| M1 | Texas Instruments | CSD19534Q5A | VdsMax= 100.0 V<br>IdsMax= 100.0 Amps | 2 | $0.34 | TRANS_NexFET_Q5A 55 mm$^2$ |
| M2 | International Rectifier | IRLR3110ZPBF | VdsMax= 100.0 V<br>IdsMax= 126.0 Amps | 2 | $0.94 | DPAK 102 mm$^2$ |
| Rcomp | Vishay-Dale | CRCW04025K90FKED<br>Series= CRCW..e3 | Res= 5.9 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 0402 3 mm$^2$ |
| Rfbb | Vishay-Dale | CRCW0402845RFKED<br>Series= CRCW..e3 | Res= 845.0 Ohm<br>Power= 63.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 0402 3 mm$^2$ |
| Rfbt | Susumu Co Ltd | RR1220P-473-D<br>Series= RR12 | Res= 47.0 kOhm<br>Power= 100.0 mW<br>Tolerance= 0.5% | 1 | $0.01 | 0805 7 mm$^2$ |
| Rsense | Susumu Co Ltd | PRL1632-R005-F-T1<br>Series= PRL1632 | Res= 5.0 mOhm<br>Power= 1.0 W<br>Tolerance= 1.0% | 1 | $0.20 | 0612 11 mm$^2$ |
| Rslope | Vishay-Dale | CRCW040290K9FKED<br>Series= CRCW..e3 | Res= 90.9 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 0402 3 mm$^2$ |
| Rt | Vishay-Dale | CRCW040230K1FKED<br>Series= CRCW..e3 | Res= 30.1 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 0402 3 mm$^2$ |
| Ruvb | Vishay-Dale | CRCW04023K40FKED<br>Series= CRCW..e3 | Res= 3.4 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 0402 3 mm$^2$ |
| Ruvt | Vishay-Dale | CRCW040249K9FKED<br>Series= CRCW..e3 | Res= 49.9 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 0402 3 mm$^2$ |
| Rvin | Vishay-Dale | CRCW12063R01FKEA<br>Series= CRCW..e3 | Res= 3.01 Ohm<br>Power= 250.0 mW<br>Tolerance= 1.0% | 1 | $0.01 | 1206 11 mm$^2$ |
| U1 | Texas Instruments | LM5122MH/NOPB | Switcher | 1 | $2.09 | MXA20A 71 mm$^2$ |

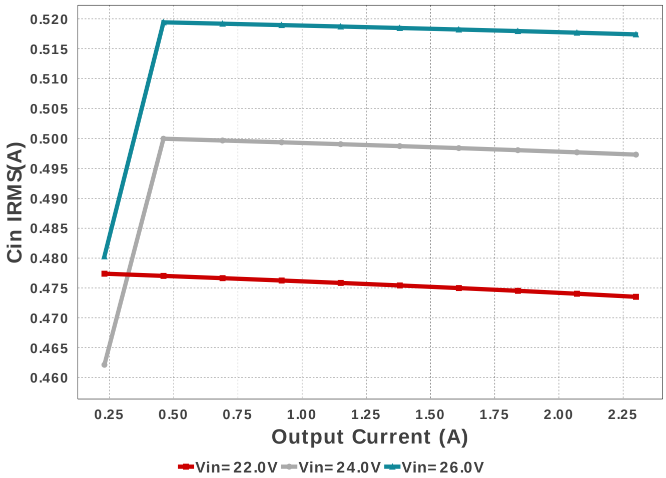
## IC Tj



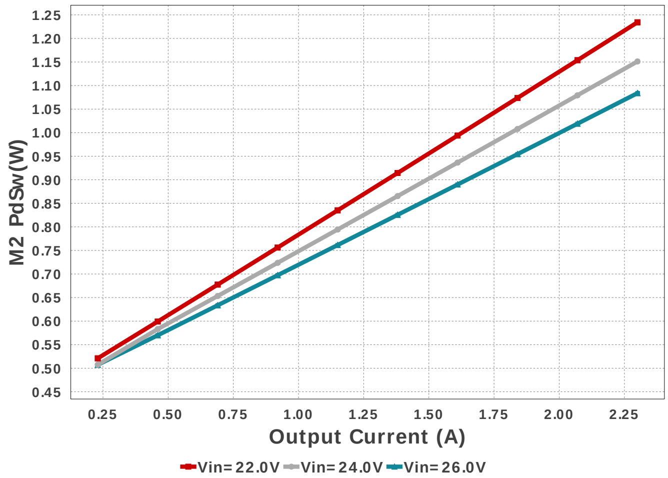

## Duty Cycle



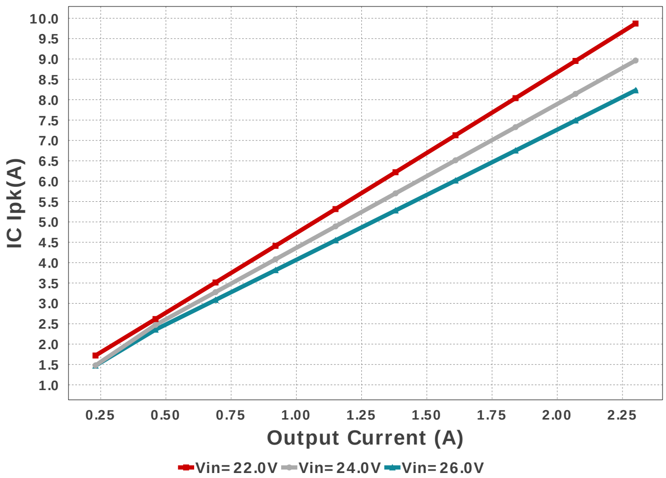

## Cin IRMS



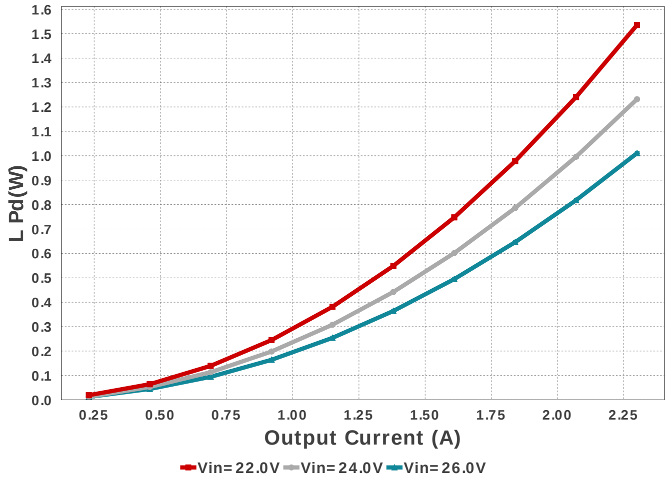

## M2 PdSw



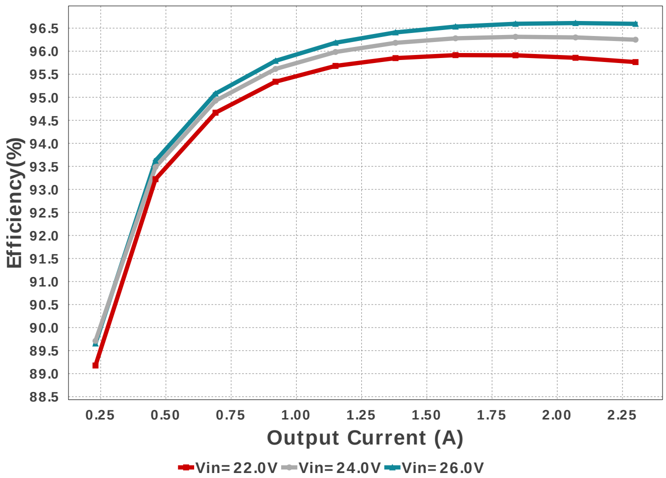

## IC Ipk



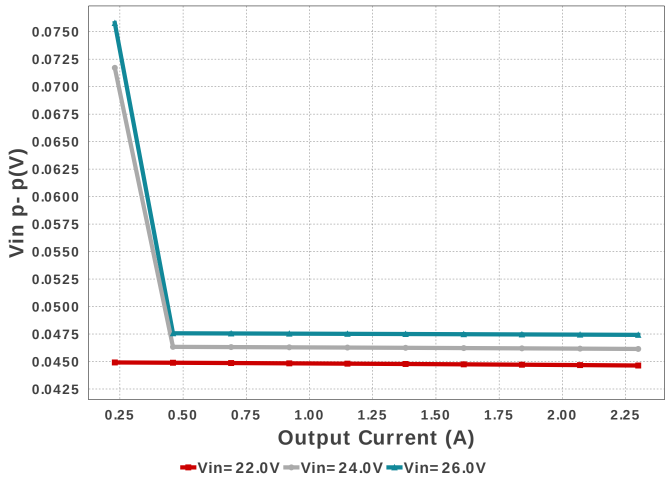

## L Pd



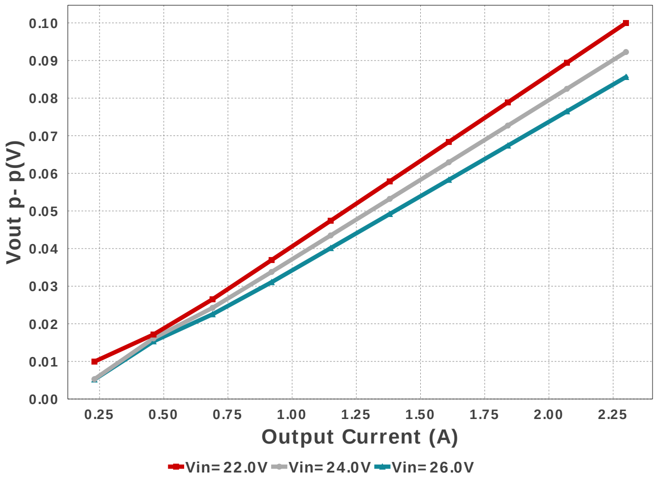
## Efficiency



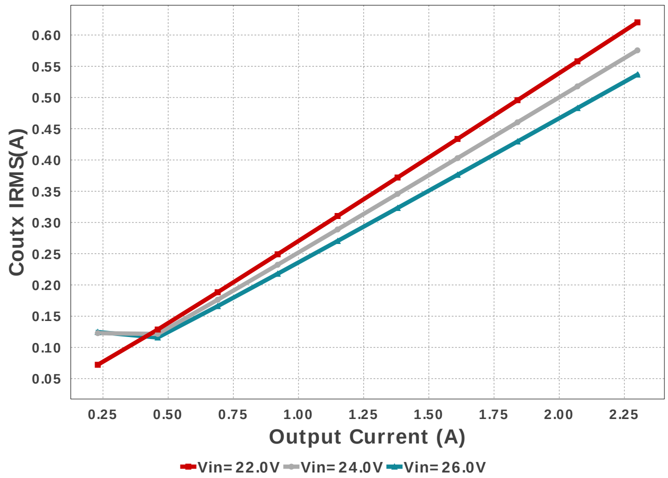

## Vin p-p



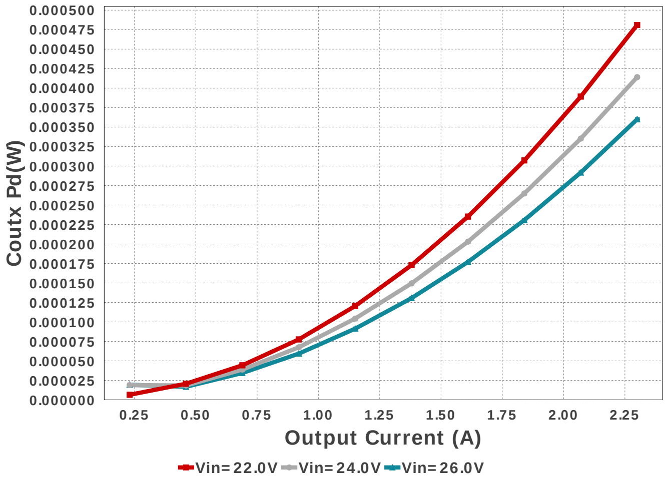

## Vout p-p



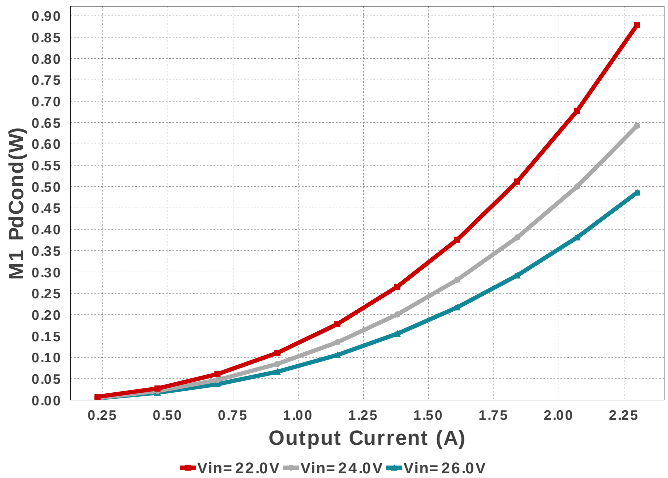

## Coutx IRMS



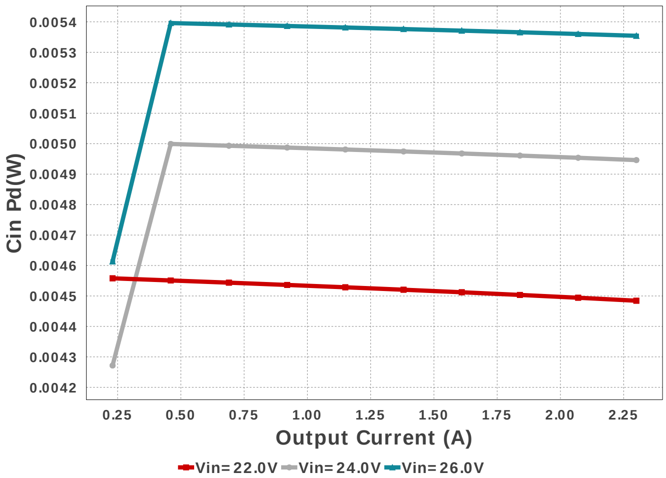

## Coutx Pd



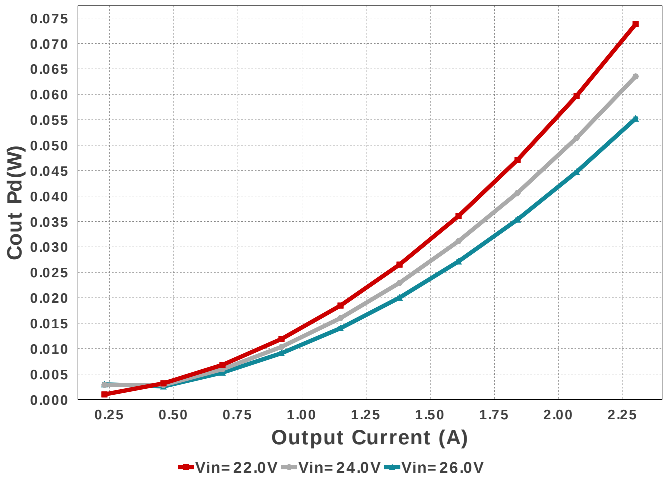

## M1 PdCond



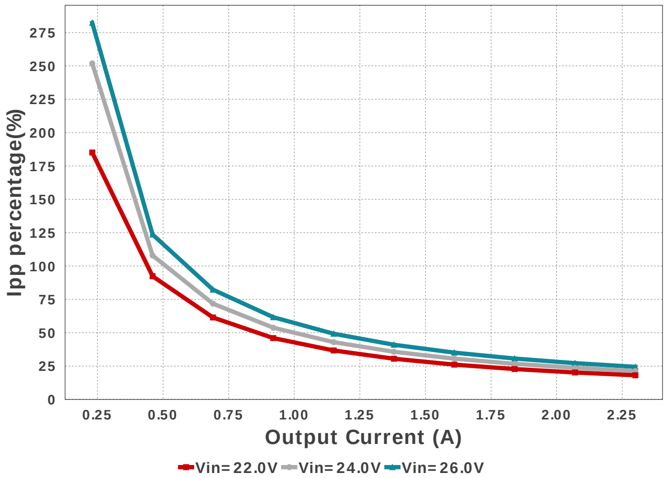
## Cin Pd



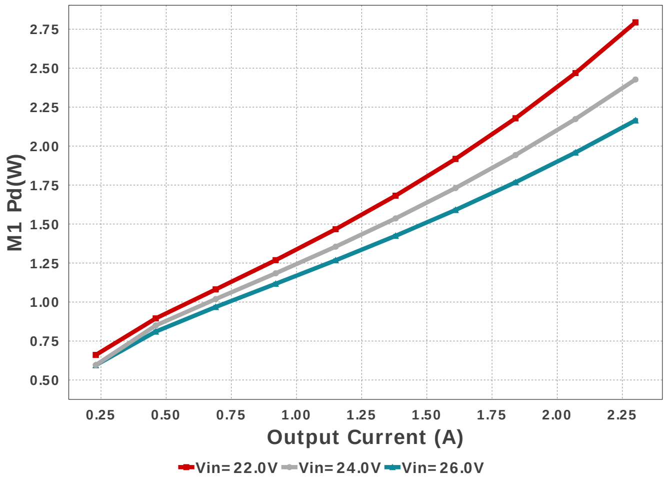

## Cout Pd



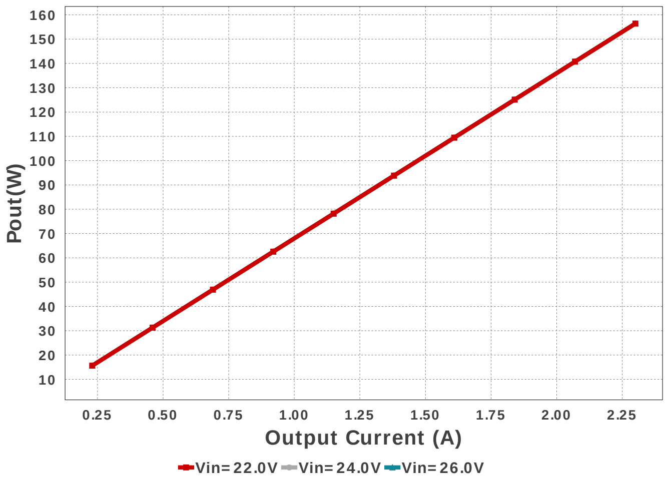

## Ipp percentage



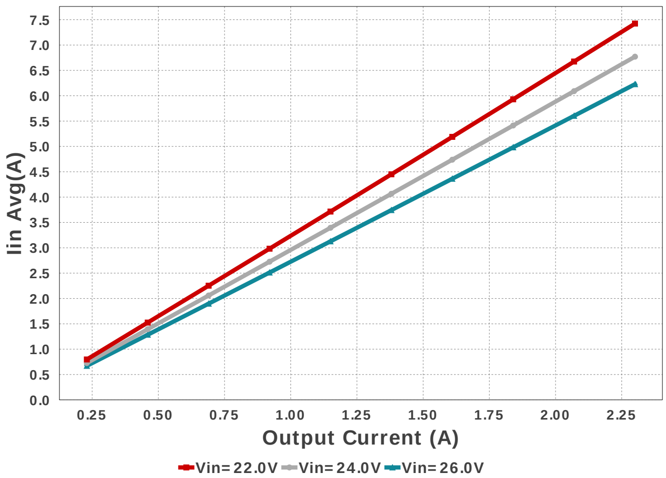

## M1 Pd



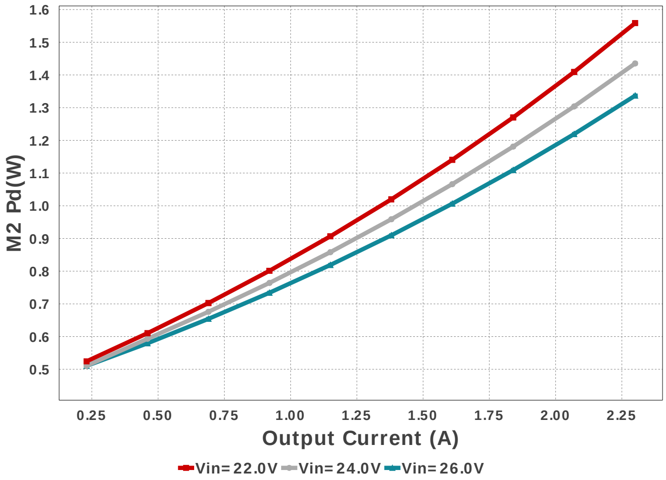

## Pout



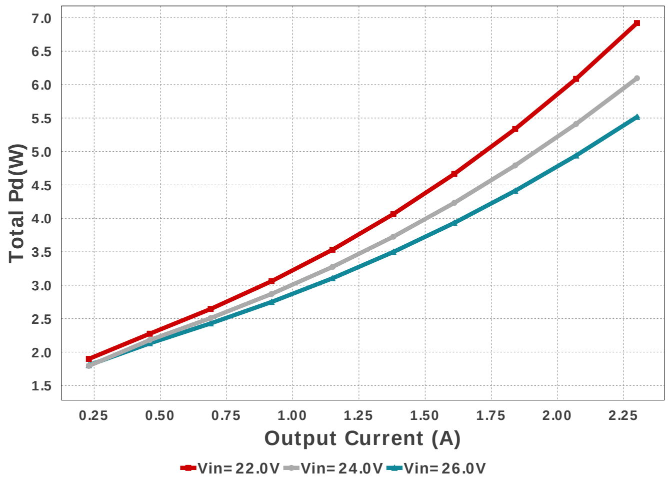

## Iin Avg



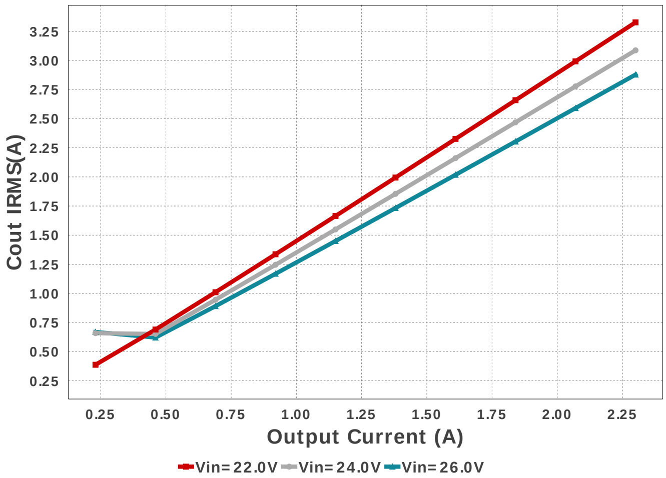
## M2 Pd



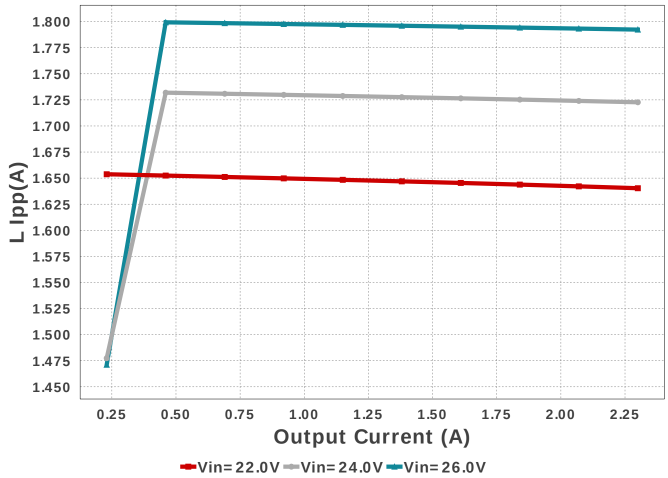

## Total Pd



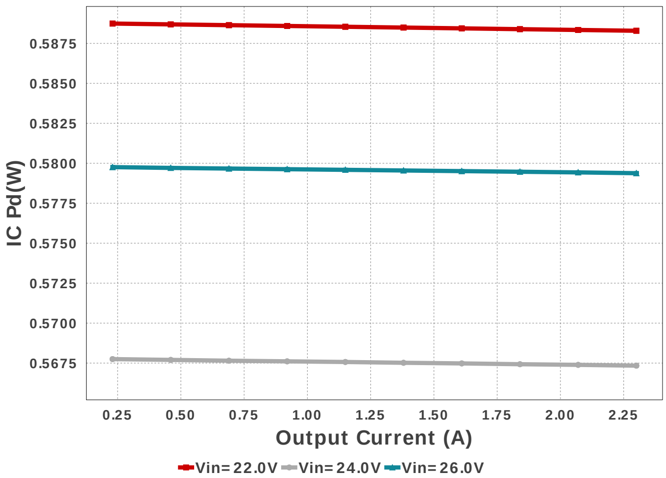

## Cout IRMS



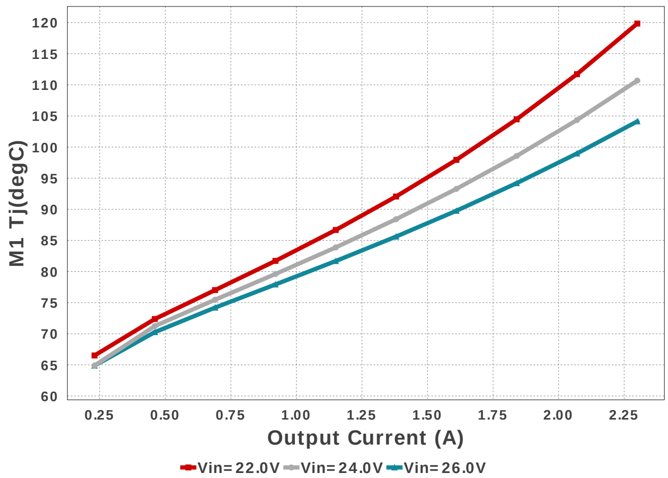

## L Ipp

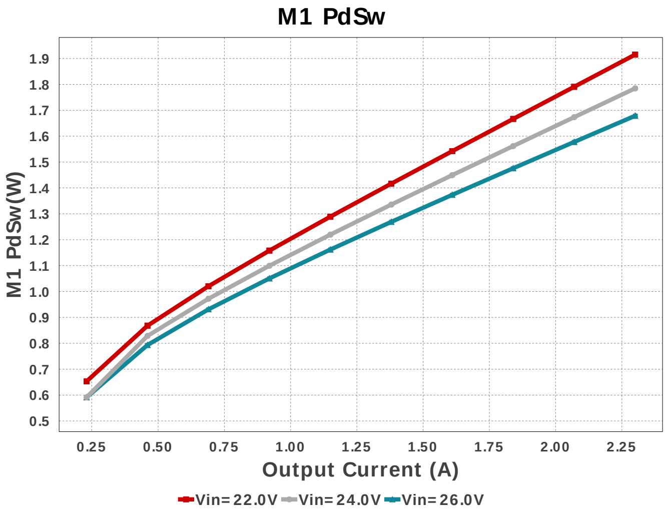


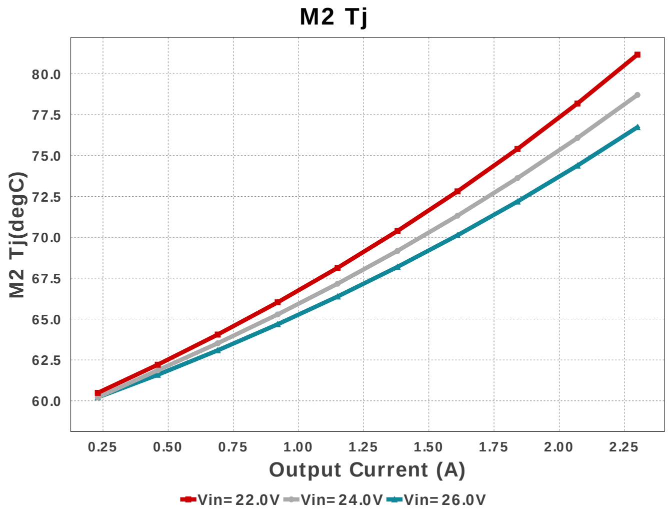

## IC Pd

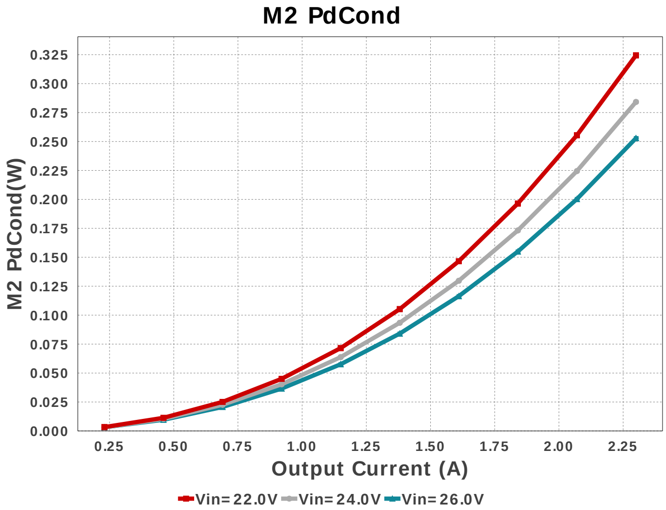


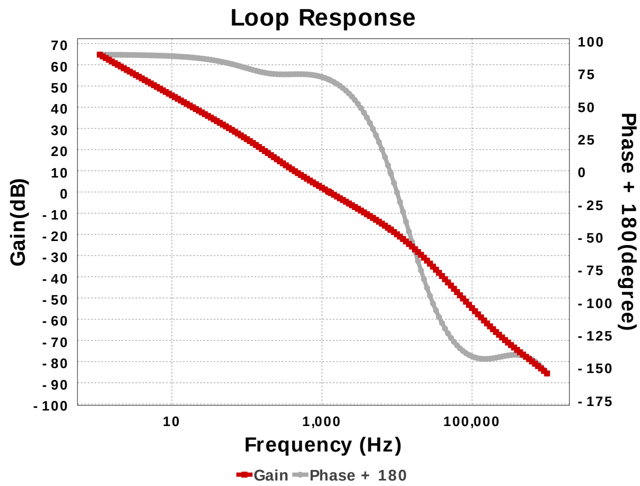

## M1 Tj






## Operating Values

| # | Name | Value | Category | Description |
|---|---|---|---|---|
| 1. | BOM Count | 37 | | Total Design BOM count |
| 2. | Total BOM | NA | | Total BOM Cost |
| 3. | Cin IRMS | 473.52 mA | Capacitor | Input capacitor RMS ripple current |
| 4. | Cin Pd | 4.484 mW | Capacitor | Input capacitor power dissipation |
| 5. | Cout IRMS | 3.327 A | Capacitor | Output capacitor RMS ripple current |
| 6. | Cout Pd | 73.785 mW | Capacitor | Output capacitor power dissipation |
| 7. | Coutx IRMS | 620.314 mA | Capacitor | Output capacitor_x RMS ripple current |
| 8. | Coutx Pd | 480.99 µW | Capacitor | Output capacitor_x power loss |
| 9. | IC Ipk | 9.869 A | IC | Peak switch current in IC |
| 10. | IC Pd | 588.29 mW | IC | IC power dissipation |
| 11. | IC Tj | 73.532 degC | IC | IC junction temperature |
| 12. | IC Tolerance | 18.0 mV | IC | IC Feedback Tolerance |
| 13. | ICThetaJA | 40.0 degC/W | IC | IC junction-to-ambient thermal resistance |
| 14. | Iin Avg | 7.424 A | IC | Average input current |
| 15. | Ipp percentage | 18.127 % | Inductor | Inductor ripple current percentage (with respect to average inductor current) |
| 16. | L Ipp | 1.64 A | Inductor | Peak-to-peak inductor ripple current |
| 17. | L Pd | 1.536 W | Inductor | Inductor power dissipation |
| 18. | M1 Pd | 2.794 W | Mosfet | M1 MOSFET total power dissipation |
| 19. | M1 PdCond | 878.81 mW | Mosfet | M1 MOSFET conduction losses |
| 20. | M1 PdSw | 1.915 W | Mosfet | M1 MOSFET switching losses |
| 21. | M1 Tj | 119.845 degC | Mosfet | M1 MOSFET junction temperature |
| 22. | M2 Pd | 1.559 W | Mosfet | M2 MOSFET total power dissipation |
| 23. | M2 PdCond | 324.41 mW | Mosfet | M2 MOSFET conduction losses |
| 24. | M2 PdSw | 1.234 W | Mosfet | M2 MOSFET switching losses |
| 25. | M2 Tj | 81.173 degC | Mosfet | M2 MOSFET junction temperature |
| 26. | Cin Pd | 4.484 mW | Power | Input capacitor power dissipation |
| 27. | Cout Pd | 73.785 mW | Power | Output capacitor power dissipation |
| 28. | Coutx Pd | 480.99 µW | Power | Output capacitor_x power loss |
| 29. | IC Pd | 588.29 mW | Power | IC power dissipation |
| 30. | L Pd | 1.536 W | Power | Inductor power dissipation |
| 31. | M1 Pd | 2.794 W | Power | M1 MOSFET total power dissipation |

| # | Name | Value | Category | Description |
|---|---|---|---|---|
| 32. | M1 PdCond | 878.81 mW | Power | M1 MOSFET conduction losses |
| 33. | M1 PdSw | 1.915 W | Power | M1 MOSFET switching losses |
| 34. | M2 Pd | 1.559 W | Power | M2 MOSFET total power dissipation |
| 35. | M2 PdCond | 324.41 mW | Power | M2 MOSFET conduction losses |
| 36. | M2 PdSw | 1.234 W | Power | M2 MOSFET switching losses |
| 37. | Total Pd | 6.92 W | Power | Total Power Dissipation |
| 38. | Cross Freq | 1.028 kHz | System Information | Bode plot crossover frequency |
| 39. | Duty Cycle | 74.583 % | System Information | Duty cycle |
| 40. | Efficiency | 95.763 % | System Information | Steady state efficiency |
| 41. | FootPrint | 1.814 k $mm^2$ | System Information | Total Foot Print Area of BOM components |
| 42. | Frequency | 299.003 kHz | System Information | Switching frequency |
| 43. | Gain Marg | -17.031 dB | System Information | Bode Plot Gain Margin |
| 44. | Iout | 2.3 A | System Information | Iout operating point |
| 45. | Low Freq Gain | 64.838 dB | System Information | Gain at 1Hz |
| 46. | Mode | CCM | System Information | Conduction Mode |
| 47. | Phase Marg | 69.305 deg | System Information | Bode Plot Phase Margin |
| 48. | Pout | 156.4 W | System Information | Total output power |
| 49. | Vin | 22.0 V | System Information | Vin operating point |
| 50. | Vin p-p | 44.636 mV | System Information | Peak-to-peak input voltage |
| 51. | Vout | 68.0 V | System Information | Operational Output Voltage |
| 52. | Vout Actual | 67.946 V | System Information | Vout Actual calculated based on selected voltage divider resistors |
| 53. | Vout Tolerance | 3.011 % | System Information | Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable |
| 54. | Vout p-p | 99.966 mV | System Information | Peak-to-peak output ripple voltage |

## Design Inputs

| Name | Value | Description |
|---|---|---|
| Iout | 2.3 | Maximum Output Current |
| SoftStart | 1.0 ms | Soft Start Time (ms) |
| VinMax | 26.0 | Maximum input voltage |
| VinMin | 22.0 | Minimum input voltage |
| Vout | 68.0 | Output Voltage |
| base_pn | LM5122 | Base Product Number |
| source | DC | Input Source Type |
| Ta | 50.0 | Ambient temperature |
| UserFsw | 600.0 k | Customer Selected Frequency |

# WEBENCH® Assembly

## Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

## Soldering Component to Board

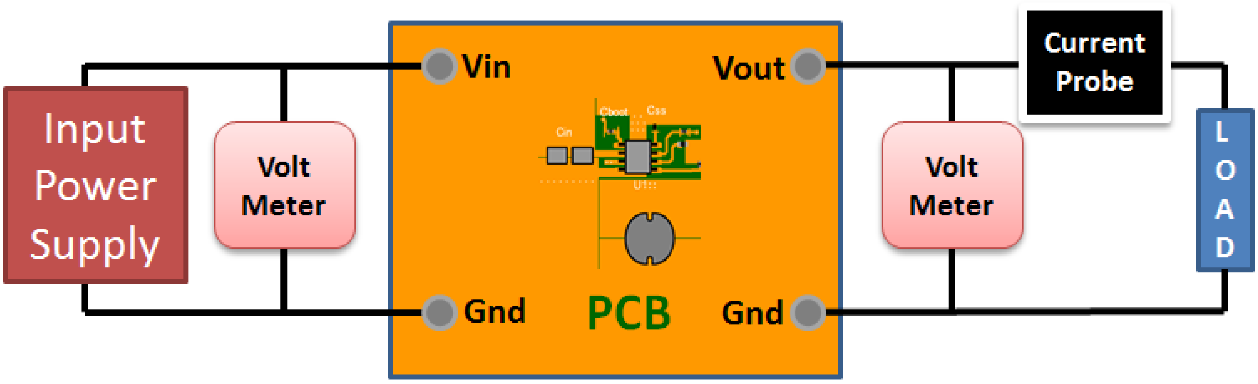
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

## Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 22.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

## Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

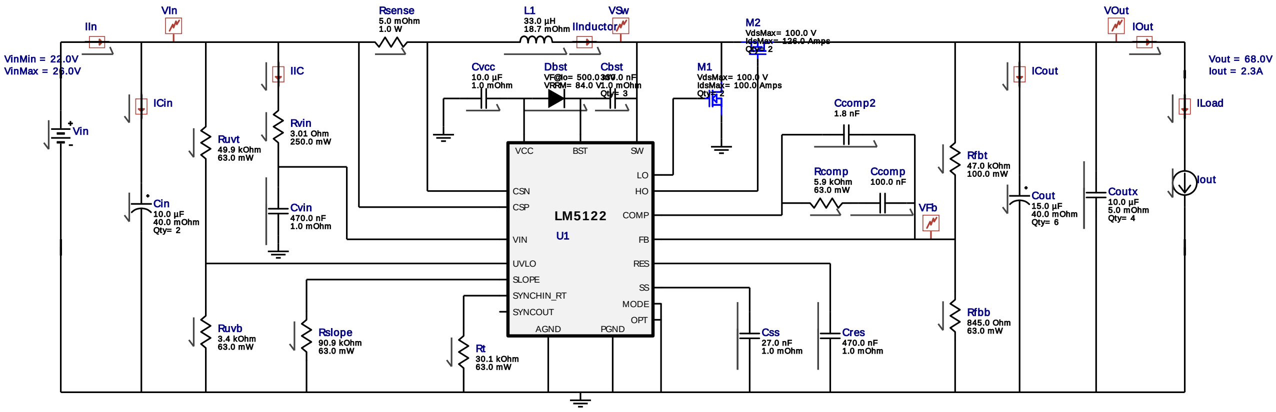


# WEBENCH® Electrical Simulation Report

Design Id = 210

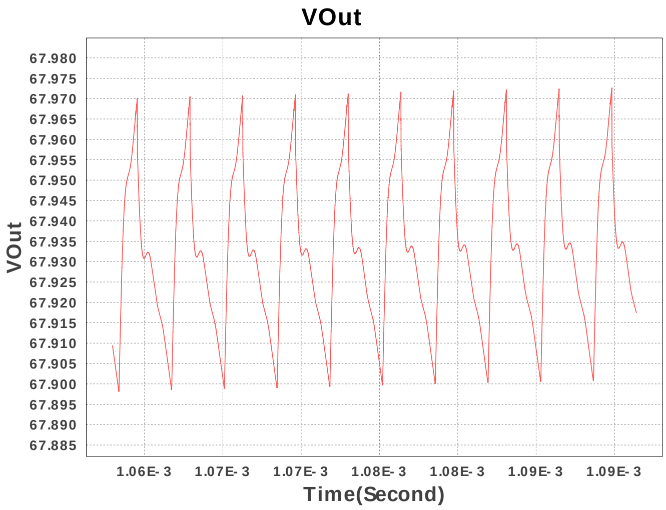
sim_id = 3

Simulation Type = Steady State




## Simulation Parameters

| # | Name | Parameter Name | Description | Values |
|---|---|---|---|---|
| 1. | Cbst | IC | Initial Condition | VinDefault V |
| 2. | Cout | IC | initial condition | 68.0 |
| 3. | Coutx | IC | initial condition | 68.0 |
| 4. | Css | IC | initial condition | 1.2 |
| 5. | Iout | I | Load Current | 2.3 A |




## Design Assistance

1. The LM5122 is a wide range boost controller which is operable in an ultra wide input range of 4.5 to 65V. A boost regulator can maintain regulation for input voltages lower than the output voltage.

2. Master key : 78FA5DFAE7FF546E[v1]

3. **LM5122** Product Folder : http://www.ti.com/product/LM5122 : contains the data sheet and other resources.

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